

**IN THE SPECIFICATION**

Please amend the paragraph beginning at page 3, lines 2-8, as follows:

Also, the inventors have found out that in the peripheral portion of the ceramic substrate (portion outer from 1/2 of the ~~diameter~~ radius of the ceramic substrate), the temperature thereof easily becomes uneven by heat radiation from the outer rim portion of the ceramic substrate. Particularly in the process in which the temperature rises (transient property), this tendency becomes significant.

Please amend the paragraph beginning at page 3, line 23, through page 4, line 1 as follows:

As a result of further investigations, the inventors have found out that by using a ceramic heater in which a resistance heating element composed of two or more circuits is arranged in the peripheral portion of a ceramic substrate (the portion outer from 1/2 of the ~~diameter~~ radius of the ceramic substrate) and further the resistance heating element composed of a different circuit is formed in the inner portion of the ceramic substrate (the portion inner from 1/2 of the ~~diameter~~ radius of the ceramic substrate), and performing detailed control of calorific value, a temperature difference on a heating face for an object to be heated, such as a semiconductor wafer, (referred to as a heating face hereinafter) can be made small so that the semiconductor wafer can be prevented from being damaged. Thus, the first aspect of the present invention has been completed.

Please amend the paragraph beginning at page 44, lines 25-30, as follows:

This formed body was drilled to make portions which would be through holes 15 into which lifter pins for supporting a semiconductor wafer would be inserted, and portions

(diameter : 1.1 mm, depth: 2 mm) which would be bottomed holes ~~[[14]]~~ into which thermocouples and supporting pins for supporting ~~thermocouples and~~ the wafer would be embedded (FIG. 6(a)).